



Material Declaration Data Sheet

Product: **Server Board S5000PSL**

Manufacturer: Intel Corporation

Date: November 9, 2006

Note:

This declaration applies to all associated product codes noted on Page 2

This product and its associated spares and accessories noted on Page 2 comply with the EU RoHS Directive 2002/95/EC.

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- ☐ 1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- ☐ 2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- ☐ 3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- ☐ 4. Lead as an alloying element in copper containing up to 4 % lead by weight.
- ☐ 5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- ☒ 6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- ☐ 7. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- ☐ 8. Lead used in compliant pin connector systems.
- ☐ 9. Lead as a coating material for the thermal conduction module c-ring.
- ☐ 10. Lead in optical and filter glass.
- ☐ 11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- ☐ 12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- ☐ 13. Cadmium in optical and filter glass.
- ☐ 14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- ☐ 15. Lead in bronze bearing shells and brushes.
- ☐ 16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

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Product Code Information

[illegible]

* RoHS Exemption # corresponds with exemption #'s found on page 1.